

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

- 5 1 (previously presented): A chip-packaging with bonding options having a plurality of package substrates, comprising:
- a first package substrate having a high voltage or a low voltage;
- a second package substrate having a high voltage or a low voltage, the voltage level of the first package substrate being the logical opposite of the voltage
- 10 level of the second package substrate; and
- a chip mounted on first package substrate, the chip comprising a plurality of bonding option pads,
- wherein each bonding option pad of the chip is associated with at least two bonding options respectively provided by the first package substrate and
- 15 the second package substrate, and each bonding option pad is connected to one of the first package substrate and the second package substrate.
- 2 (cancelled).
- 20 3 (previously presented): The chip-packaging of the claim 1 wherein the high voltage is the voltage of the power supply and the low voltage is the ground voltage.
- 4 (currently amended): The chip-packaging of the claim 1 further comprising a plurality of leads, wherein each lead is connected to a high voltage, a low voltage, or an
- 25 one pin of the chip-packaging.
- 5-6 (cancelled).

7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.

5 8 (previously presented): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding option pads.

9-19 (cancelled).

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20 (previously presented): The chip-packaging of the claim 1 further comprising a plurality of leads, each bonding option pad of the chip having a corresponding lead, wherein each bonding option pad is connected to one of the first package substrate, the second package substrate, and the corresponding lead.

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21 (new): The chip-packaging of the claim 1 wherein each bonding option pad is connected to one of the first package substrate and the second package substrate for determining the functionality of the chip.

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